L Number	Hits	Search Text	DB	Time stamp
-	9015	(438/106-127).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:26
-	0	((438/106-127).CCLS.) and ((SiC or carbide) with die) and (BPSG with (adhesive or encapsul$6)) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:27
-	0	((438/106-127).CCLS.) and ((SiC or carbide) with die) and (BPSG with (adhesive or encapsul$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:27
-	0	((438/106-127).CCLS.) and (SiC or carbide) and (BPSG with (adhesive or encapsul$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:27
-	264	((438/106-127).CCLS.) and (SiC or carbide) and ((adhesive or encapsul$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:28
-	37	(((438/106-127).CCLS.) and (SiC or carbide) and ((adhesive or encapsul$6))) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:27
-	16	((438/106-127).CCLS.) and ((SiC or carbide) with die) and ((adhesive or encapsul$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 14:28
-	0	((SiC or carbide) with die) and (BPSG with (adhesive or encapsul$6)) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:19
-	1	((SiC or carbide) with die) and (BPSG) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:38
-	2	("5909354" | "5981913").PN.	USPAT	2004/09/13 17:22
-	0	((SiC or carbide)) and (BPSG) and (AlN with adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:38
-	108	((SiC or carbide)) and (BPSG) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 11:10
-	4	((SiC or carbide)) and (doped adj glass) and AlN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 11:21
-	64	SiC with metal with junction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 14:04
-	2	("6319757").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 16:00

-	27268	(257/678-733).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 16:01
-	46	((257/678-733).CCLS.) and (((silicon adj carbide) or SiC) with die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 17:39
-	31	chip and (adhesive with (BSG or borosilicate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 18:22
-	0	chip and ((gold or Au) same ((silicon adj carbide) or SiC)) same ((adhesive with (BSG or borosilicate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 17:42
-	55	chip and ((SiC or (silicon adj carbide)) with (BSG or borosilicate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 18:23
-	4	("4695733" | "5025243" | "5122668" | "5868497").PN.	USPAT	2004/09/14 18:31
-	3	(thermal with conductive with properties with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:15
-	12	(thermal with conductive with electrical with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:33
-	23	(thermal with electrically with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:34
-	169	(thermal$3 with electrical$3 with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:34
-	157	((thermal$3 with electrical$3 with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))) not ((thermal with conductive with electrical with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:35
-	60	(((thermal$3 with electrical$3 with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))) not ((thermal with conductive with electrical with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt)))) and semiconduct$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:23
-	0	borosilica with encapsula$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:25
-	0	borosilica with encapsula$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:25

-	4	bsg with encapsula$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:25
-	89	(bsg or borosilicate) with encapsula$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:01
-	197	(buried adj oxide) and (deep with source with drain)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:11